

Patent Abstracts of Japan

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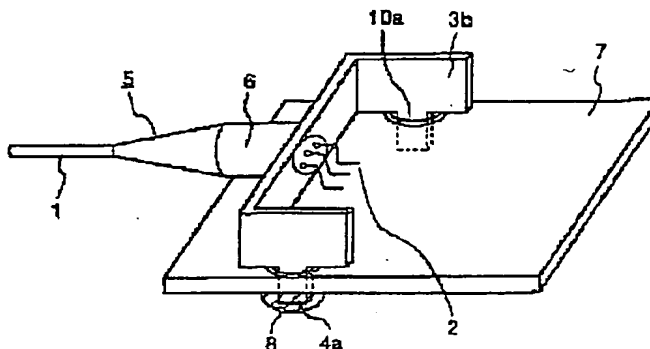
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TITLE : OPTICAL SEMICONDUCTOR
ELEMENT MODULE AND OPTICAL
SEMICONDUCTOR DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To simply and firmly fix an optical semiconductor element module and a printed board, to reduce assembling manhour and to suppress the deterioration of optical and electrical characteristics of the module in an optical semiconductor device constituted of packaging the module on the printed board.

SOLUTION: A cylindrical metallic case 6 for an optical semiconductor element module 5 storing a part optically connecting an optical fiber 1 to an optical semiconductor element in the case 6 is provided with a terminal-attached flange 3b allowed to be soldered to the board 7. Structure for shielding a front end part improves a shielding effect and suppresses the deterioration of optical and electrical characteristics of the module 5.

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